New Generation Inspection Technology for PCBA
WV-1806Q-330E

Launch in 2017 from Nagano

**High resolution 18M 4 USB cameras
Compact & Low-price with no drives**

**Easy & quick setting
No need of skill for inspection for SMT**

**Optimized for defect detection
up to 0.6x0.3mm chips**

**Ultra high-speed inspection to any
number of parts**

Offline desktop model (photo)
Inline model with the same function available
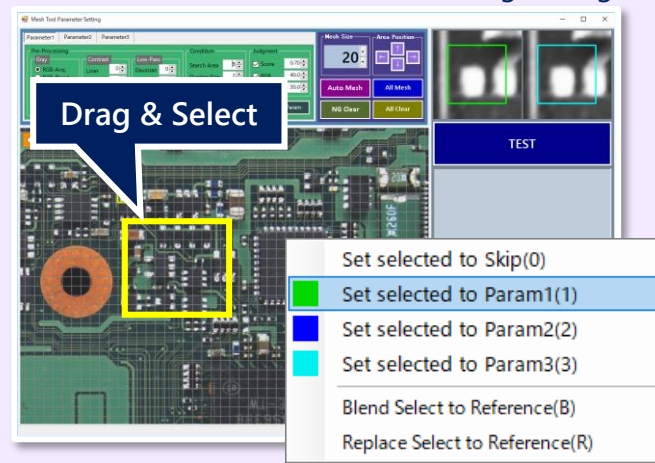Contact us for larger and special PCBA

Mesh Matching software (Patent Pending) originally designed eliminates the workload for parts library designating an inspection area by pointing with the mouse.

In place of 3D functions, cumbersome to set up and less robust, the RGB image offers rich and specific information necessary for the line, which represents a breakthrough to conventional AOI systems in size and investment.

In addition to the standard automatic image storage, bar code serial reading is available as an option. Plug-in software that conforms to your system is customized on demand.
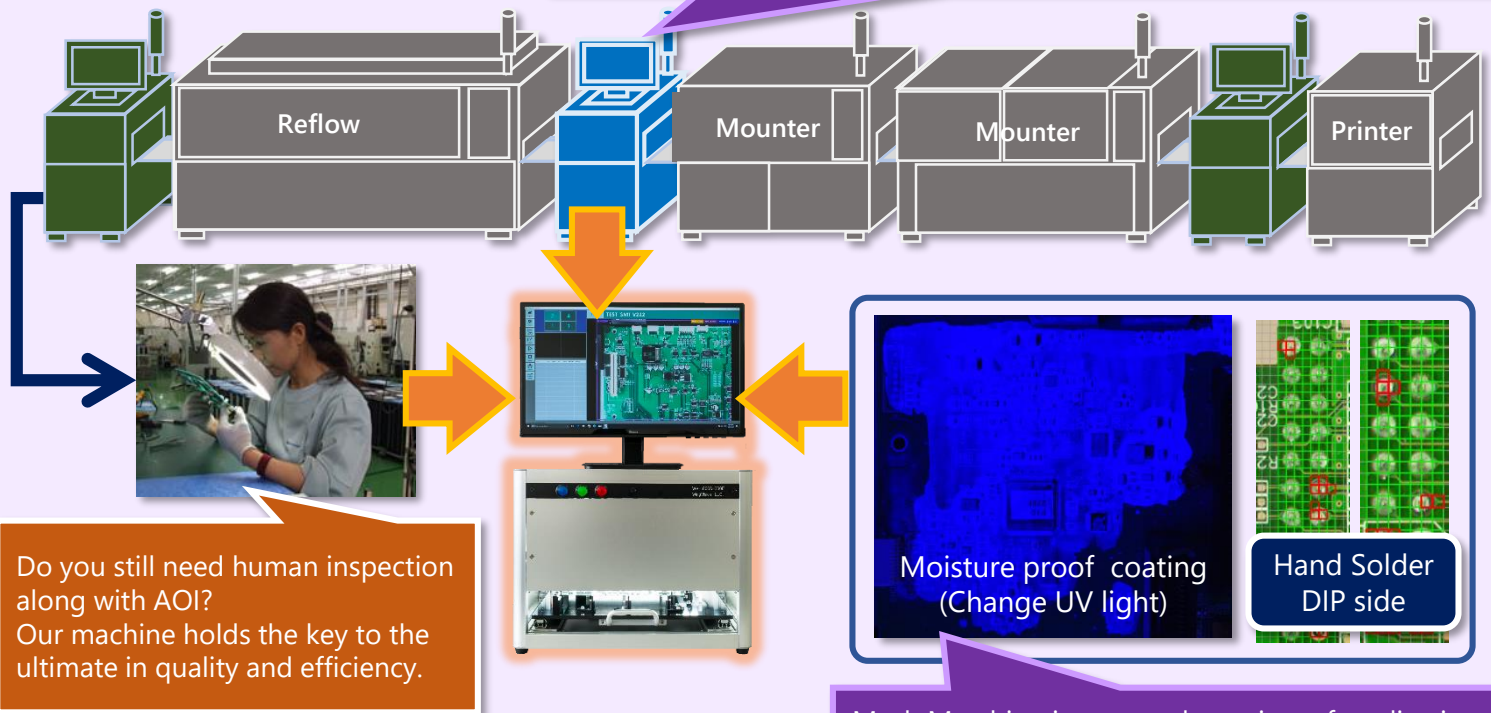
Mesh Matching setting

Drag & Select

TEST

Set selected to Skip(0)
Set selected to Param1(1)
Set selected to Param2(2)
Set selected to Param3(3)
Blend Select to Reference(B)
Replace Select to Reference(R)

**Inspection ready within 1 hour of setting
PCBA with 3,000 points on one side**

Perfect Solution for small & variety production

YKT corporation
www.ykt.co.jp

WingVision LLC.
www.wvision-llc.com

Recommended process

Best to install WV-1806-330 inline before reflow. By detecting NG before soldering hardened, secondary defects at repair are prevented, and quality is built upstream by quick feedback to a mounter and a printer.

Reflow | Mounter | Mounter | Printer

Do you still need human inspection along with AOI?
Our machine holds the key to the ultimate in quality and efficiency.

Moisture proof coating (Change UV light)

Hand Solder DIP side

Mesh Matching increases the variety of applications playing an SPC role, including some inspection that cannot be evaluated clearly with numerical values.

Specification

Item	Specification
Model	WV-1806Q-330 (J) WV-1806Q-330E (EU)
PCB size	50mm(X), 50mm(Y) – 330mm(X), 250mm(Y) Thickness of board 0.4mm - 3.0mm
Component size	Minimum chip : 0.6mm(X), 0.3mm(Y) Max Height : 20mm Max number of component : No limit
Camera and Lens	18Mega pixels USB3.0 CMOS 4 cameras 6mm Focal length 5MPixel resolution lens
Detection target	Shortage, Direction, Misregistration, Upside-down, Solder-ball, Bridge, etc. 1D/2D bar code reading (option)
Inspection time	5-20 seconds (Variable according to area)
Optical resolution	37μm/pixel
Illumination	High brightness white flat LED x 4 directions
PC	CPU: Intel Core-i3 Memory：8Gbytes OS: Windows10
Monitor	21inch Full-HD (HDMI connection)
Power supply	AC 100V 50/60Hz(J) DC24V 42W max(EU)
Machine size	500mm(width), 380mm(depth), 380mm(height without monitor) Weight : 23kg(J), 21kg(EU)